

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DU HO KIM	11/12/2021
DEOK KWAN CHOI	11/12/2021
MIN HEO	11/12/2021
KANG MIN KIM	11/12/2021
SOO MIN JEON	11/15/2021
A RA LEE	11/15/2021
WON GON KIM	11/12/2021
JI HOON PARK	11/12/2021
HYUN WOO SHIM	11/12/2021
TAE HO BANG	11/15/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	HYUNDAI MOBIS CO., LTD.
<b>Street Address:</b>	203, TEHERAN-RO, GANGNAM-GU
<b>City:</b>	SEOUL
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	06141
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17551819
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2027393000
<b>Email:</b>	patents@morganlewis.com, Sandra.Johnson@morganlewis.com
<b>Correspondent Name:</b>	MORGAN LEWIS & BOCKIUS LLP
<b>Address Line 1:</b>	1111 PENNSYLVANIA AVENUE NW
<b>Address Line 4:</b>	WASHINGTON, D.C. 20004
<b>ATTORNEY DOCKET NUMBER:</b>	129255-5042-US

<b>NAME OF SUBMITTER:</b>	SANDRA JOHNSON
<b>SIGNATURE:</b>	/Sandra Johnson/
<b>DATE SIGNED:</b>	12/15/2021
<b>Total Attachments: 3</b> source=129255-5042-US_declaration#page1.tif source=129255-5042-US_declaration#page2.tif source=129255-5042-US_declaration#page3.tif	



I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and


Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.


NAME OF INVENTOR (Full Legal Name): Du Ho KIM

Signature:  Date: 12 Nov. 2021

NAME OF INVENTOR (Full Legal Name): Deok Kwan CHOI

Signature:  Date: 12 NOV. 2021

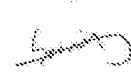
NAME OF INVENTOR (Full Legal Name): Min HEO

Signature:  Date: 12 NOV. 2021

NAME OF INVENTOR (Full Legal Name): Kang Min KIM

Signature:  Date: 12 Nov. 2021


NAME OF INVENTOR (Full Legal Name): Soo Min JEON



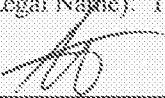
Signature:  Date: 19 Nov. 2021

NAME OF INVENTOR (Full Legal Name): A Ra LEE

Signature:  Date: 2021.11.15

NAME OF INVENTOR (Full Legal Name): Won Gon KIM

Signature:  Date: 2021.11.12

NAME OF INVENTOR (Full Legal Name): Ji Hoon PARK	
Signature: 	Date: 2021. 11. 12
NAME OF INVENTOR (Full Legal Name): Hyun Woo SHIM	
Signature: 	Date: 2021. 11. 12
NAME OF INVENTOR (Full Legal Name): Tae Ho BANG	
Signature: 	Date: 2021. 11. 12

*Morgan, Lewis & Bockius LLP*